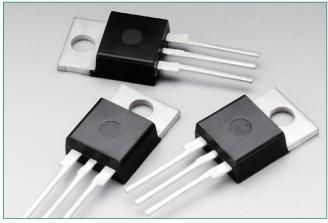
Surface Mount - 400V - 800V







Description

The MAC12x is designed for high performance full-wave AC control applications where high noise immunity and commutating di/dt are required.

Features

- Blocking Voltage to 800 Volts
- On-State Current Rating of 12 Amperes RMS at 70°C
- Uniform Gate Trigger Currents in Three Quadrants, Q1, Q2,
- High Immunity to dv/dt 250 V/µs Minimum at 125°C
- High Commutating di/dt 6.5 A/ms Minimum at 125°C
- Industry Standard TO-220
- High Surge Current Capability - 100 Amperes
- These Devices are Pb-Free and are RoHS Compliant

Additional Information



Resources



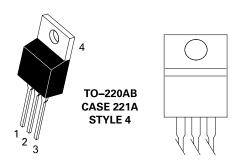


Samples

Functional Diagram



Pin Out



Surface Mount - 400V - 800V

Maximum Ratings (TJ = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit	
Peak Repetitive Off-State Voltage (Note 1) MAC12D MAC12M (Gate Open, Sine Wave 50 to 60 Hz, $T_J = 40^{\circ}$ to 125°C) MAC12N		V _{DRM} , V _{RRM}	400 600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, $T_c = 7$	0°C)	I _{T (RMS)}	12	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, T _i = 125°C)		I _{TSM}	100	А
Circuit Fusing Consideration (t = 8.3 ms)		l²t	41	A²sec
Peak Gate Power (Pulse Width \leq 1.0 μ s, $T_c = 80$ °C)		P _{GM}	16	W
Average Gate Power (t = 8.3 ms, T_c = 80°C)		P _{G(AV)}	0.35	W
Operating Junction Temperature Range		T_{J}	-40 to +125	°C
Storage Temperature Range		T _{stg}	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the

Thermal Characteristics

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R _{ejc} R _{eja}	2.2 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds		T_L	260	°C

Electrical Characteristics - OFF (TJ = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T ₁ = 25°C	I _{DRM} ,	-	-	0.01	m Λ
$(V_D = V_{DRM} = V_{RRM}$; Gate Open)	T _J = 125°C	IRRM	-	-	2.0	mA

Electrical Characteristics - ON (TJ = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Peak On–State Voltage (Note 2) ($I_{TM} = \pm 11 \text{ A}$)		V_{TM}	-	-	1.85	V
Gate Trigger Current	MT2(+), G(+)		5.0	13	35	mA
(Continuous dc)	MT2(+), G(-)	I _{GT}	5.0	13	35	
$(V_{D} = 12 \text{ V}, \text{ R}_{L} = 100 \Omega)$	MT2(-), G(-)		5.0	13	35	
Holding Current ($V_D = 12 \text{ V}$, Gate Open, Initiating Current = $\pm 150 \text{ mA}$))	I _H	-	20	40	mA
	MT2(+), G(+)	IL	_	20	50	mA
Latching Current $(V_D = 24 \text{ V}, I_G = 35 \text{ mA})$	MT2(+), G(-)		_	30	80	
(v _D = 24 v, i _G = 33 mm)	MT2(-), G(-)		_	20	50	
0 . 7:	MT2(+), G(+)		0.5	0.78	1.5	
Gate Trigger Voltage $(V_D = 12 \text{ V}, R_I = 100 \Omega)$	MT2(+), G(-)	$V_{\rm GT}$	0.5	0.70	1.5	V
(v _D = 12 v, 11 _L = 100 12)	MT2(-), G(-)		0.5	0.71	1.5	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different

2. Indicates Pulse Test: Pulse Width \leq 2.0 ms, Duty Cycle \leq 2%



Recommended Operating Conditions may affect device reliability.

1. V_{DBM} and V_{BBM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Surface Mount - 400V - 800V

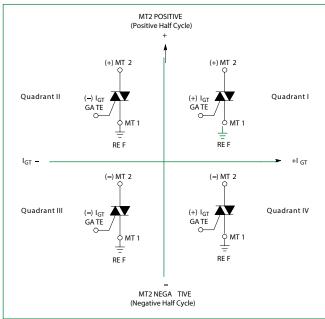
Dynamic Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
Rate of Change of Commutating Current See Figure 10. ($V_D = 400 \text{V}$, $I_{TM} = 4.4 \text{A}$, Commutating dv/dt = 18 V/µs,Gate Open, $T_J = 125 ^{\circ}\text{C}$, f = 250 Hz, No Snubber)	di/dt _(C)	6.5	-	-	A/ms
Critical Rate of Rise of Off-State Voltage $(V_D = Rated V_{DRM}, Exponential Waveform, Gate open, T_J = 125°C)$	dV/dt	250	500	_	V/µs
Repetitive Critical Rate of Rise of On-State Current IPK = 50 A; PW = 40 µsec; diG/dt = 200 mA/µsec; f = 60 Hz	di/dt	-	-	10	A/µs

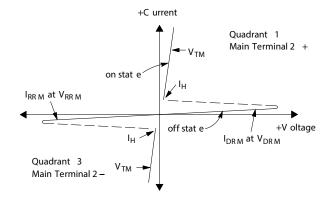
Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off State Voltage
I _{DRM}	Peak Forward Blocking Current
$V_{_{\mathrm{RRM}}}$	Peak Repetitive Reverse Off State Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Maximum On State Voltage
l _u	Holding Current

Quadrant Definitions for a Triac



All polarities are referenced to MT1.
With in –phase signals (using standard AC lines) quadrants I and III are used



Surface Mount - 400V - 800V

Figure 1. Typical Gate Trigger Current vs Junction Temperature

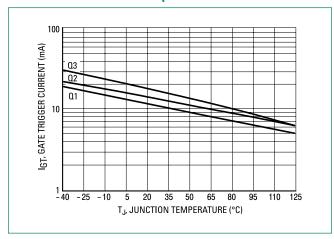


Figure 3. Typical Holding Current vs Junction Temperature

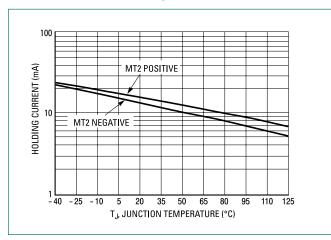


Figure 5. Typical RMS Current Derating

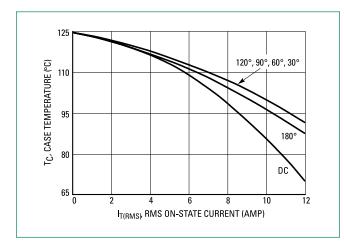


Figure 2. Typical Gate Trigger Voltage vs Junction Temperature

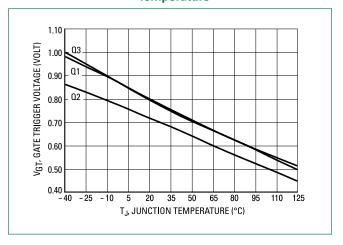


Figure 4. Typical Latching Current vs Junction Temperature

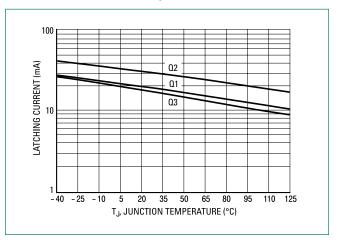
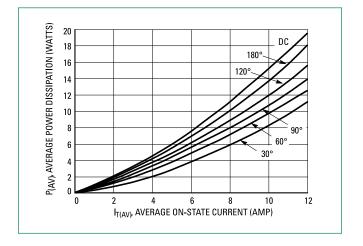


Figure 6. On-State Power Dissipation





Surface Mount – 400V - 800V

Figure 7. Typical On-State Characteristics

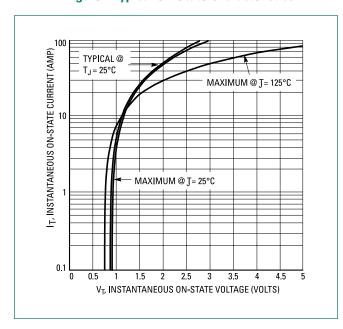
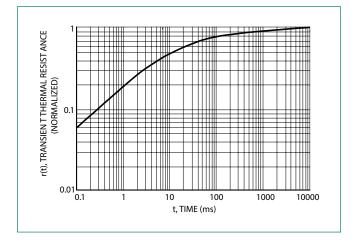


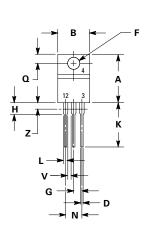
Figure 8. Typical Thermal Response

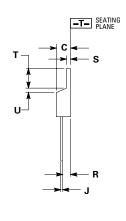




Surface Mount - 400V - 800V

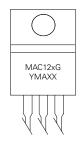
Dimensions





Part Marking System





x =D, M, or N Y =Year

M =Month A =Assembly Site

XX =Lot Serial Code

G =Pb-Free Package

Dim	Inches		Millin	neters
Dim	Min	Max	Min	Max
Α	0.590	0.620	14.99	15.75
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
Н	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	_
Z		0.080		2.04

Pin Assignment			
1	Main Terminal 1		
2	Main Terminal 2		
3	Gate		
4	No Connection		

Ordering Information

Device	Package	Shipping
MAC12DG	TO 000 4 D	
MAC12MG	TO-220AB (Pb-Free)	1000 Units / Box
MAC12NG	(1 5 1100)	

2. Controlling dimension: inch.



^{1.} Dimensioning and tolerancing per ansi y14.5m, 1982.

^{3.} Dimension z defines a zone where all body and lead irregularities are allowed.

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BTB16Q-600BW Z0409MF BTA04-600B BTA06-600BRG BTA06-800BWRG BTA08-600BRG BTA08-800B BT136-600,127

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